

Reliability and Test Condition

Item	Performance	Test Condition
Solderability	More than 90% of the terminal electrode shall be covered with fresh solder	Preheat : 125 ± 25°C for 60 sec Solder : 99%Sn/0.3%Ag/0.7%Cu Or Equivalent Solder Temp : 245 ± 5°C Flux: Rosin Dip Time: 4±1 sec
Thermal Shock Test		Room Temp. $\xrightarrow{\hspace{1cm}}$ $\frac{-25\pm 2^{\circ}\text{C}}{30 \text{ Minutes}}$ 15 Minutes Room Temp. $\xrightarrow{\hspace{1cm}}$ $\frac{85\pm 2^{\circ}\text{C}}{30 \text{ Minutes}}$ 15 Minutes Total: 50 Cycles
Humidity Resistance Test	Inductance shall not change more than ±20%	Temperature: 40 ± 2°C. Humidity: 90 ~ 95% RH Applied Current: Per sec Time: 500 hrs.
Humidity Temperature Resistance Test		Temperature: 85 ± 2°C. Applied Current: Per sec Time: 500 hrs.

